

# Chip Scale Review®

ChipScaleReview.com

The Future of Semiconductor Packaging

## 2017 Editorial Calendar

(Editorial close date: 4/21)

July • August

\* indicates show distribution

FOWLP	<ul style="list-style-type: none"><li>• <b>ICEPT 2017</b> Harbin, China (Aug 16-19)</li><li>• <b>SEMICON Taiwan *</b> Taipei, Taiwan (Sept 13-15)</li><li>• <b>BiTS China 2017</b> TBD, China (TBD)</li><li>• <b>European MEMS Summit</b> Grenoble, France (Sept 20-22)</li></ul>
WLP surface processing	
Wafer probing	
CSP hermetic packaging	
TSV technologies	
Die attach solutions	
3D metrology challenges	
HVM challenges of die bonding	

Ad Space Close Jun 24 - Ad Materials Close Jul 1

(Editorial close date: 6/9)

September • October

\* indicates show distribution

FOWLP & panel-level processes update	<ul style="list-style-type: none"><li>• <b>IMAPS 2017 *</b> Raleigh, NC, CA (Oct 9-12)</li><li>• <b>IWLPC-International Wafer-Level Packaging Conference &amp; Exhibition *</b> San Jose, CA (Oct 24-26)</li><li>• <b>International Test Conference (ITC)</b> Fort Worth, TX (Oct 31- Nov 2)</li><li>• <b>MEMS Executive Congress</b> Napa Valley, CA (Nov 1-2)</li><li>• <b>SEMICON Europa</b> Munich, Germany (Nov 14-17)</li></ul>
Consortia collaboration	
Packaging ICs/sensors for automotive applications	
Advanced interconnects	
Thermal interface materials	
Final test	
Packaging SiPs/SiP supply chain	
Chip / package interaction	
Advanced embedded packaging for power devices	

Ad Space Close Sep 9 - Ad Materials Close Sep 16

(Editorial close date: 9/1)

November • December

\* indicates show distribution

2.5D & 3D ICs	<ul style="list-style-type: none"><li>• <b>SEMICON Japan</b> Tokyo, Japan (Dec 13-15)</li><li>• <b>3D ASIP Conference *</b> Burlingame, CA (TBD)</li><li>• <b>SEMI European 3D Summit *</b> Grenoble, France (TBD)</li></ul>
Stacked die CSPs	
China market update	
Dicing & singulation	
Silicon Photonics update	
Thermal management of ICs	
Thermocompression bonding	
IC cleaning process	

Ad Space Close Nov 4 - Materials Close Nov 11

For ad inquiries: [ads@chipscalereview.com](mailto:ads@chipscalereview.com) - For editorial inquiries [editor@chipscalereview.com](mailto:editor@chipscalereview.com)

Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.

Haley Publishing Inc.2017 All rights reserved. Rev:CSR-EC-032317